

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SHINGO TAJIMA	06/04/2014
RECEIVING PARTY DATA		
Name:	MICRON TECHNOLOGY, INC.	
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PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	16230699
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ATTORNEY DOCKET NUMBER:	P244732US03	
NAME OF SUBMITTER:	DENISE SHERIDAN	
SIGNATURE:	/Denise Sheridan/	
DATE SIGNED:	12/21/2018	
Total Attachments: 2		
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Shingo Tajima

Filed : Concurrently herewith

For : SEMICONDUCTOR DEVICE
HAVING A REDUCED FOOTPRINT
OF WIRES CONNECTING A DLL
CIRCUIT WITH AN INPUT/OUTPUT
BUFFER

Docket No. P244732.US.01

Disclosure No. ELPA-0093.00/US

A S S I G N M E N T:

X Enclosed for recording
 Previously recorded

Date: _____

Reel: _____

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN AND TRANSFER to **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "SEMICONDUCTOR DEVICE HAVING A REDUCED FOOTPRINT OF WIRES CONNECTING A DLL CIRCUIT WITH AN INPUT/OUTPUT BUFFER", which claims priority to JP patent application, filed on June 25, 2013, assigned Application No. 2013-132800 and is entitled "SEMICONDUCTOR DEVICE"; such application and any legal equivalent thereof in a foreign country, including the right to claim priority and, in and to, all Letters Patent to be obtained for said invention by the above application or any and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Signature: Shingo Tajima
Assignor Name: Shingo Tajima

Date: June 4, 2014

Witness # 1:
Signature: Shoji Eguchi

Date: June 4, 2014

Witness Name: Shoji Eguchi

Witness # 2:
Signature: _____

Date: _____

Witness Name: _____